



F16.2

FORM A FIRST DIE AND A SECONDDIE 3/2 ATTACH THE SECOND DIE TO THE FIRST DIE 314 ATTACH THE FIRST DIE TO A MULTI-LAYER SUBSTRATE 3/6 ATTACH BONDING WIRES TO CIRCUIT BONDING PADS AND PACKAGE BONDING PADS

F16. 3

FORM A FIRST DIE, A SECOND DIE, AND A THIRD DIE SELECT A DIE FROM THE GROUP OF DICE INCLUDING THE SECOND DIE AND THE THIRD DIE ATTACH THE SELECTED DIE TO THE FIRST DIE 416 ATTACH THE FIRST DIE TO A MULTI-LAYER SUBSTRATE 418 ATTACH BONDING WIRES TO CIRCUIT BONDING PADS AND PACKAGE BONDING PADS

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